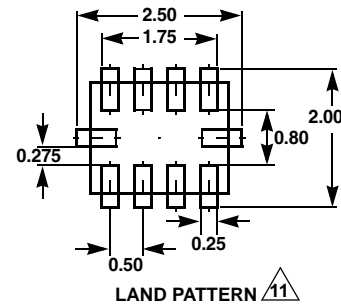
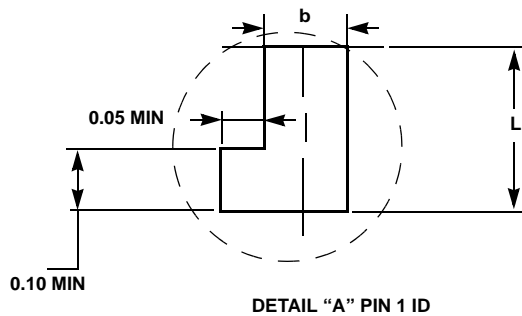
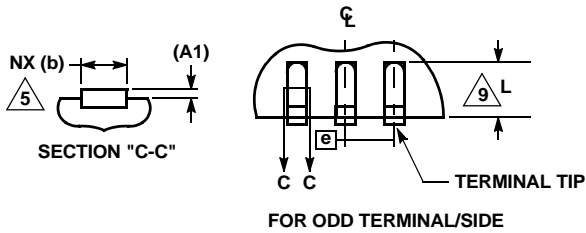
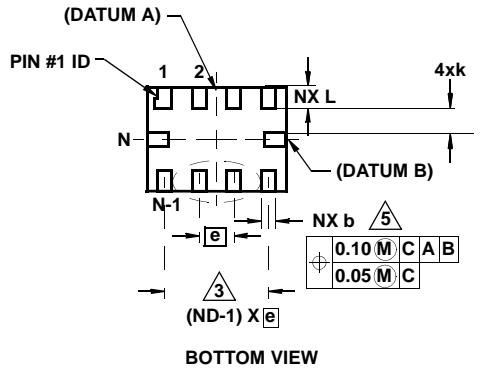
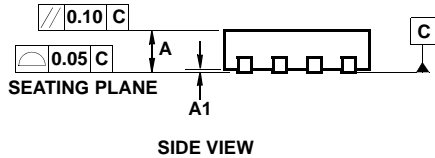
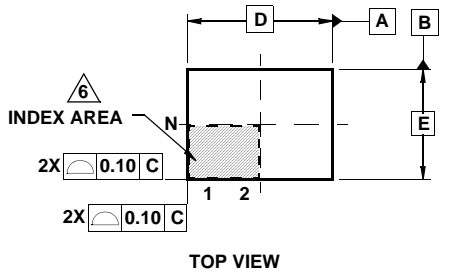


Thin Quad Flat No-Lead Plastic Package (TQFN)



L10.2.1x1.6B

10 LEAD THIN QUAD FLAT NO-LEAD PLASTIC PACKAGE

SYMBOL	MILLIMETERS			NOTES
	MIN	NOMINAL	MAX	
A	0.50	0.55	0.60	-
A1	-	-	0.05	-
A3	0.14 REF			-
b	0.15	0.20	0.25	5, 9
D	2.05	2.10	2.15	-
E	1.55	1.60	1.65	-
e	0.50 BSC			-
k	0.20	-	-	-
L	0.35	0.40	0.45	9
N	10			2
Nd	4			3
Ne	1			3
θ	0	-	12	4

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NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
2. N is the number of terminals.
3. Nd and Ne refers to the number of terminals on D and E side, respectively.
4. All dimensions are in millimeters. Angles are in degrees.
5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
7. Maximum package warpage is 0.05mm.
8. Maximum allowable burrs is 0.076mm in all directions.
9. Nominal dimensions are provided to assist with PCB Land Pattern Design efforts, see Intersil Technical Brief TB389.
10. Same as JEDEC MO-255WABD except:
No lead-pull-back,
"L" MAX dimension = 0.45 not 0.42mm.
11. For additional information, to assist with the PCB Land Pattern Design effort, see Intersil Technical Brief TB389.